

47. (Added) The method of claim 46, further comprising capping the amalgamation layer.
48. (Added) The method of claim 47, wherein capping the amalgamation layer comprises introducing an additional blending material to the amalgamation layer.
49. (Added) An electronic component formed by the method of claim 46.
50. (Added) The electronic component of claim ~~47~~⁴⁹, wherein the component comprises a circuit board, a resistor, an inductor, a capacitor, a solder point, a solder connector, a mother board or a combination thereof.
51. (Added) A method of forming a film, the method comprising
providing a nanoporous aerogel precursor material;
treating the nanoporous aerogel precursor material to form a nanoporous aerogel;
providing a blending material having a reinforcing component and a volatile component;
combining the nanoporous aerogel and the blending material to form an amalgamation layer; and
treating the amalgamation layer to remove a substantial amount of the volatile component, thereby increasing the mechanical strength of the amalgamation layer and decreasing the dielectric constant of the film.
52. (Added) The method of claim ~~49~~⁵¹, further comprising capping the amalgamation layer.
53. (Added) The method of claim ~~50~~⁵², wherein capping the amalgamation layer comprises introducing an additional blending material to the amalgamation layer.
54. (Added) A film formed by the method of claim ~~49~~⁵¹.
55. (Added) An electronic component comprising the film of claim ~~52~~⁵¹.
56. (Added) A layered material comprising the film of claim ~~52~~⁵¹.

IN THE SPECIFICATION

Insert the following before "Field of the Invention":

This application is a divisional of allowed application Serial Number 10/189,318, filed July 3, 2002.